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1621 BARBER LANE, M/S D-106
MILPITAS, CA 95035

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MAY 05 2004

In re Application of:	:	
Pekin et al.	:	
Application No. 10/757,752	:	DECISION GRANTING
Filed: January 14, 2004	:	PETITION UNDER
Title of Invention:	:	37 CFR 1.47(a)
OPTOMIZED BOND OUT METHOD FOR FLIP :	:	
CHIP WAFERS	:	

OFFICE OF PETITIONS

This is in response to a Petition under 37 CFR 1.47(a), filed with the instant application on January 14, 2004, to allow the other inventor(s) to proceed with the application on behalf of himself or herself and the nonsigning inventor.

The petition is granted.


The above-identified application and papers have been reviewed and found in compliance with 37 CFR 1.47(a). This application is hereby accorded Rule 1.47(a) status.

Petitioner has shown that the non-signing inventor, Senol Pekin, refuses to join in the application.

As provided in Rule 1.47(a), this Office will forward notice of this application's filing to the non-signing inventor at the addresses given in the Petition. Notice of the filing of this application will also be published in the Official Gazette.

The application file is being returned to the Office of Initial Patent Examination for continued processing.

Telephone inquiries related to this decision may be directed to the undersigned at (703) 305-0014.


Derek L. Woods
Petitions Attorney
Office of Petitions



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Mr. Senol Pekin
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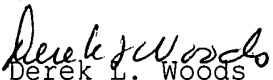
In re Application of: :
Pekin et al. :
Application No. 10/757,752 : LETTER
Filed: January 14, 2004 :
Title of Invention: :
OPTOMIZED BOND OUT METHOD FOR FLIP :
CHIP WAFERS :

Dear Mr. Pekin:

You are named as an inventor in the above-identified United States patent application filed under the provisions of 35 U.S.C. 116 (United States Code) and 37 CFR 1.47(b), Rules of Practice in Patent Cases. Should a patent be granted on the application you will be designated therein as a joint inventor.

As a named inventor you are entitled to inspect any paper in the file wrapper of the application, order copies of all or any part thereof (at a prepaid cost per 37 CFR 1.19) or make your position of record in the application. Alternatively, you may arrange to do any of the preceding through a registered patent attorney or agent presenting written authorization from you. If you care to join the application, counsel of record (see below) would presumably assist you. Joining in the application would entail the filing of an appropriate oath or declaration by you pursuant to 37 CFR 1.63.

Telephone inquiries regarding this communication should be directed to the undersigned at (703) 305-0014. Requests for information regarding your application should be directed to the File Information Unit at (703) 308-2733. Information regarding how to pay for and order a copy of the application, or a specific paper in the application, should be directed to Certification Division at (703) 308-9726 or 1-800-972-6382 (outside the Washington D.C. area).


Derek L. Woods
Petitions Attorney
Office of Petitions

cc: LSI LOGIC CORPORATION
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